
















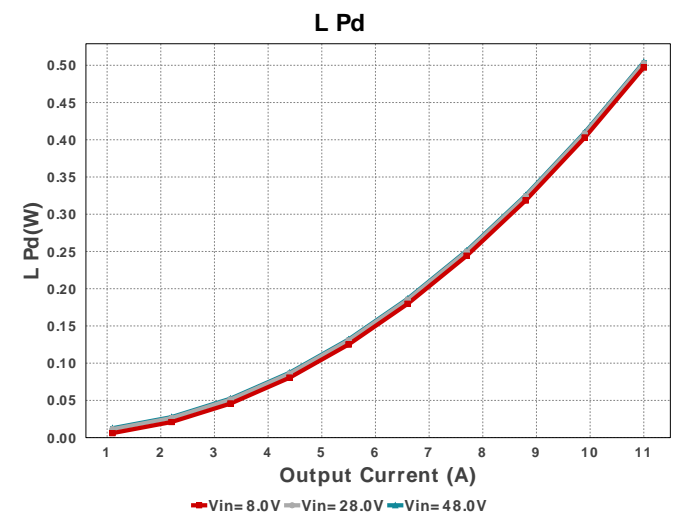
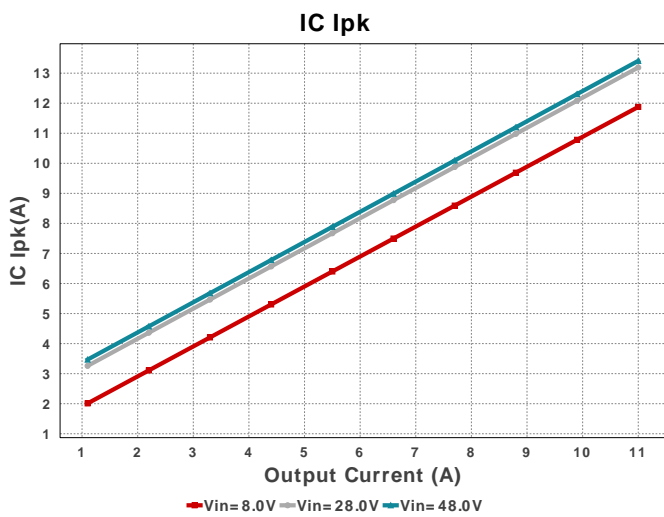
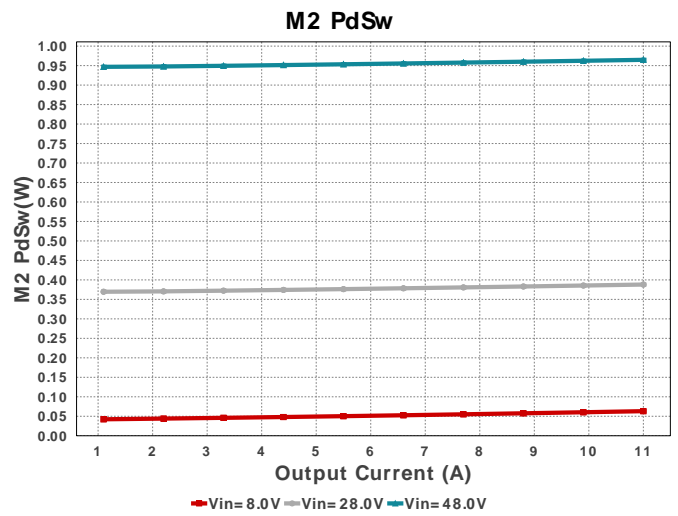
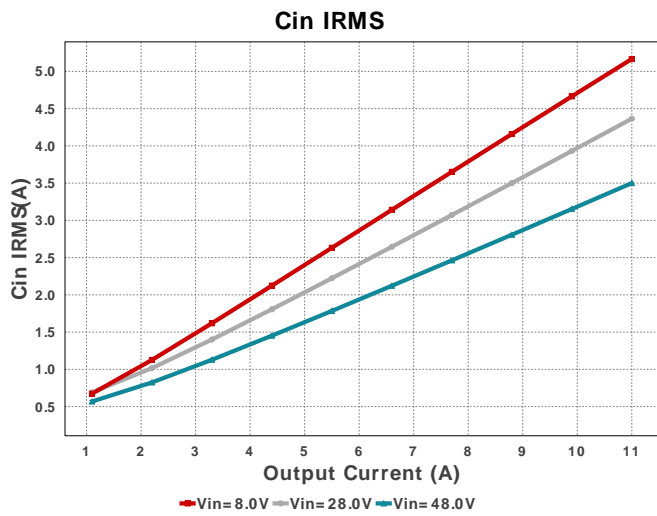
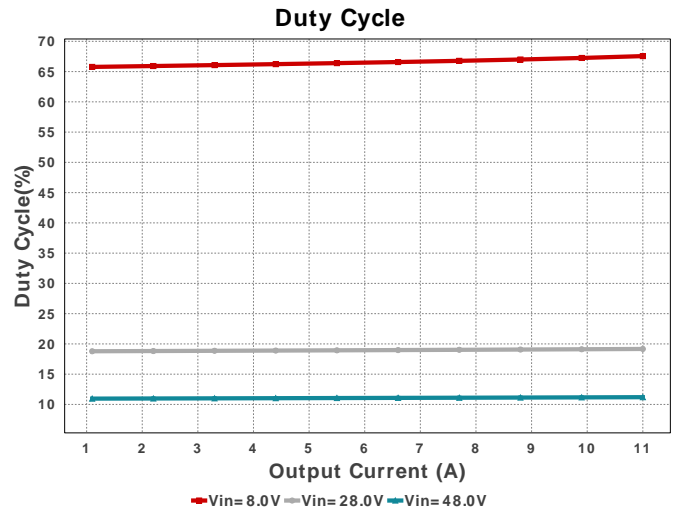
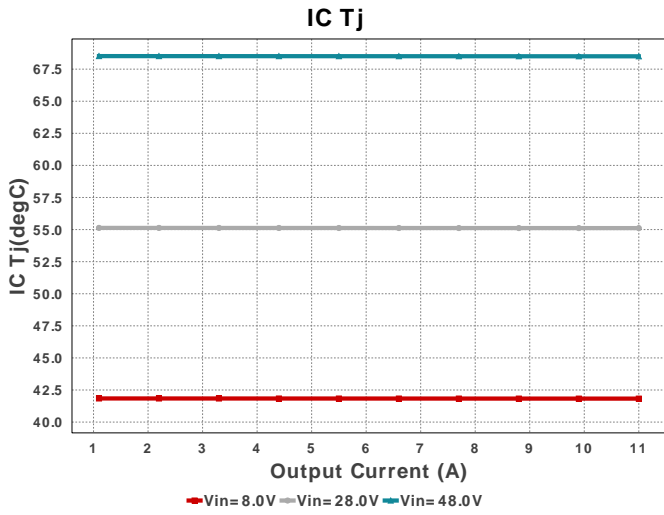
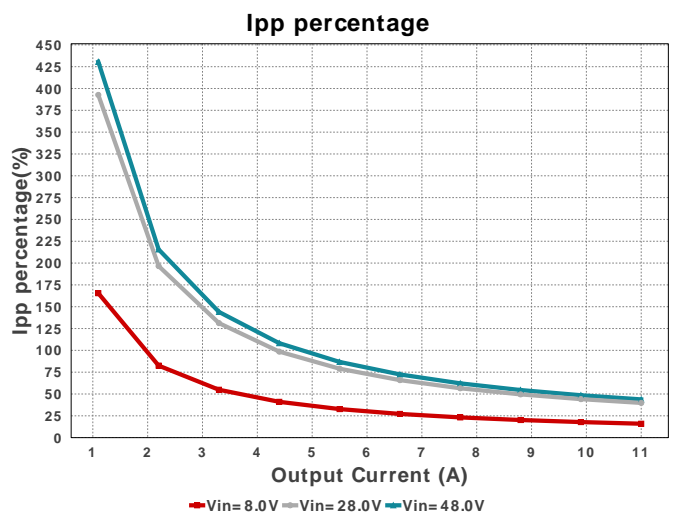
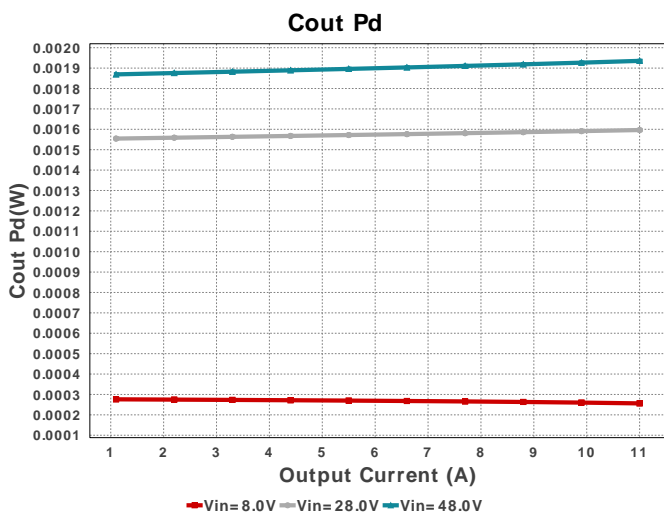
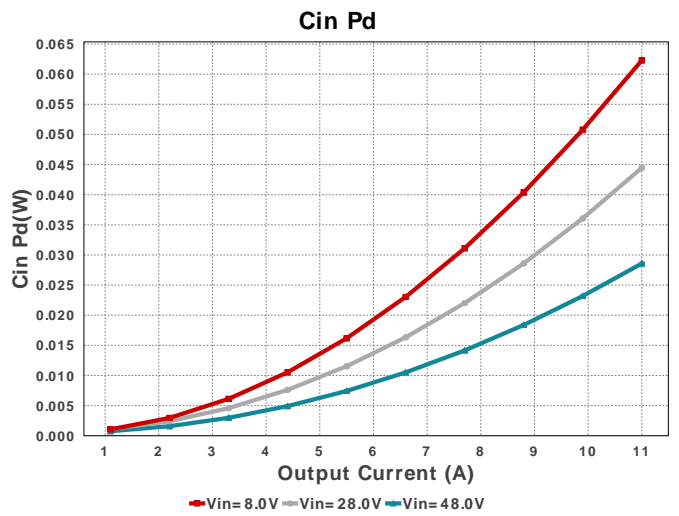
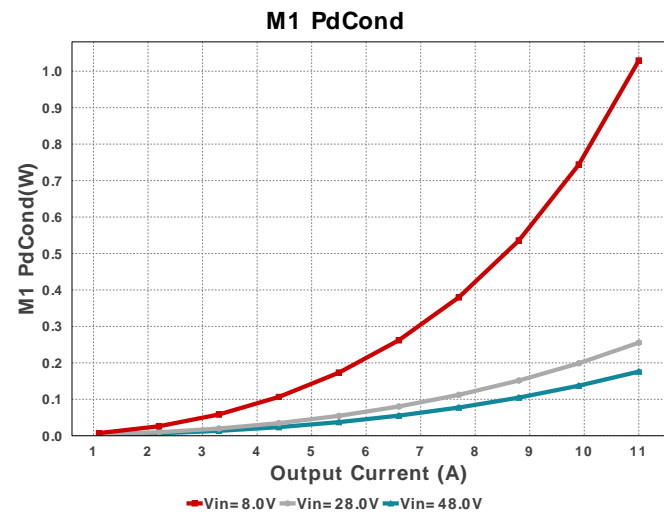
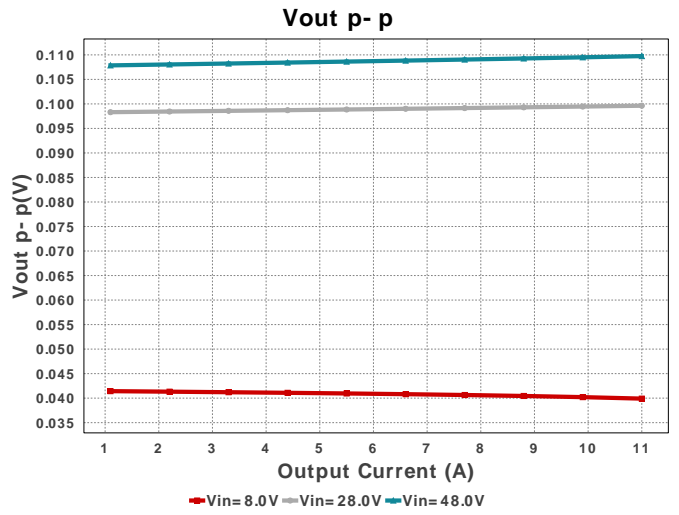
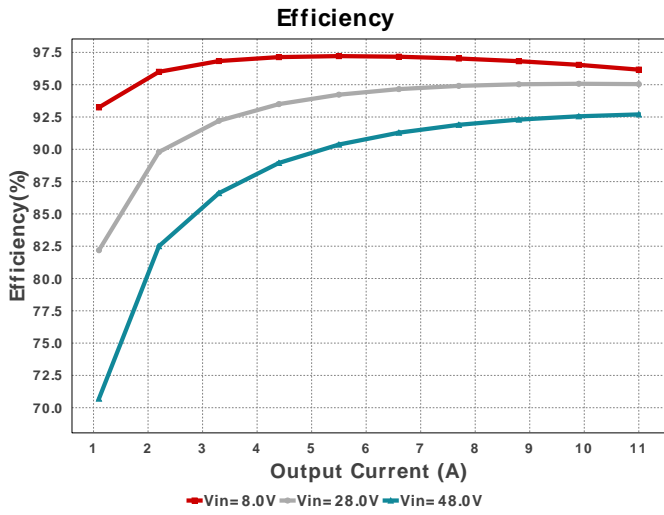
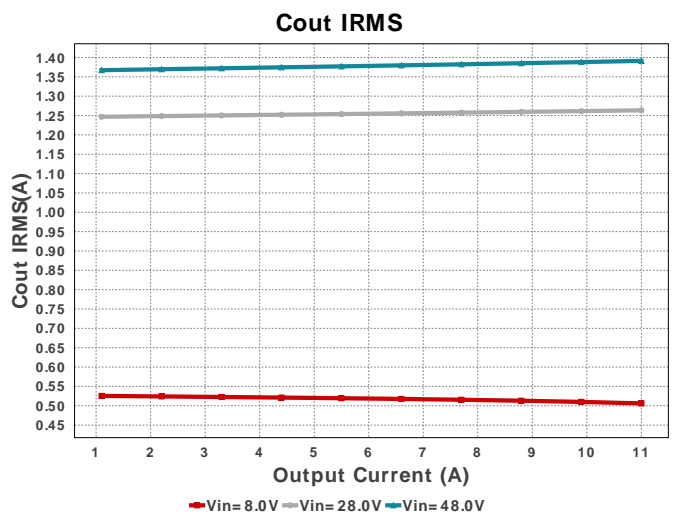
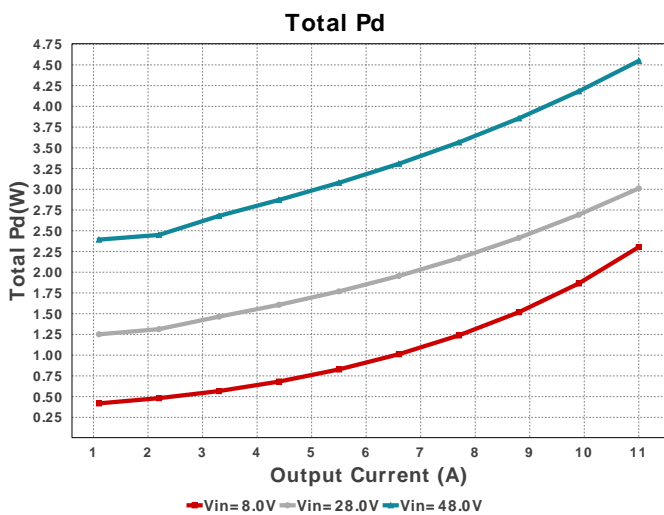
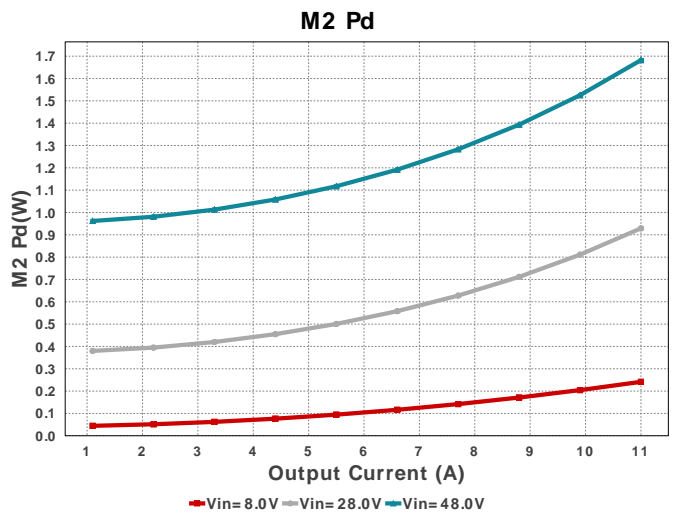
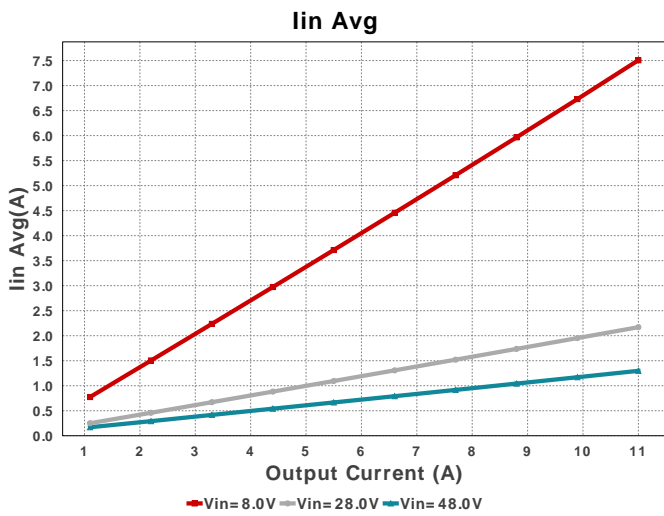
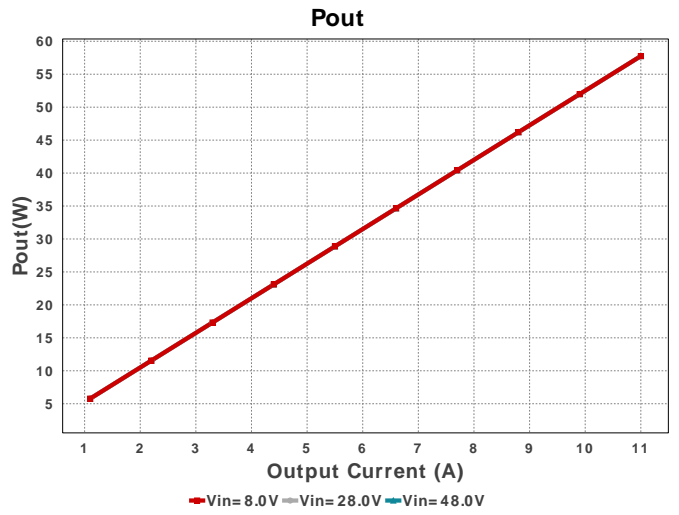
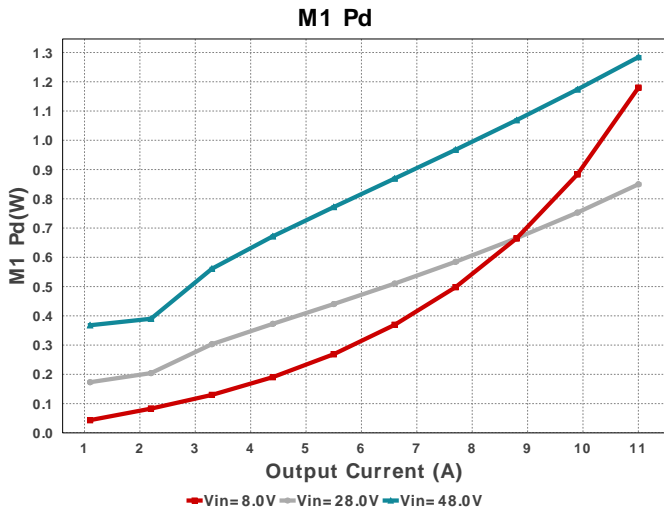
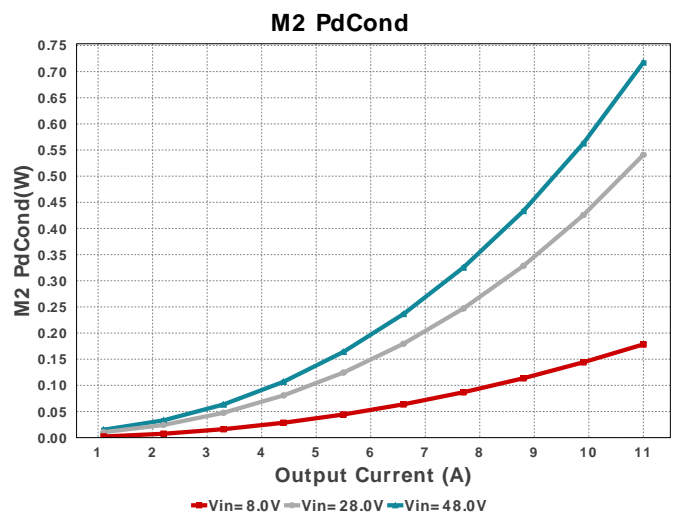
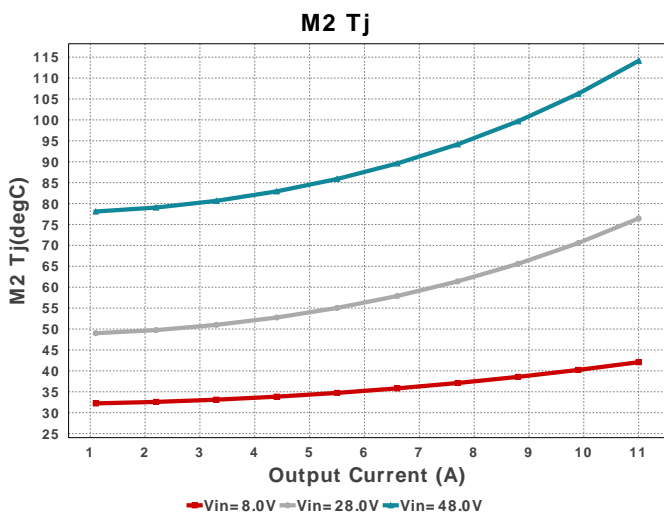
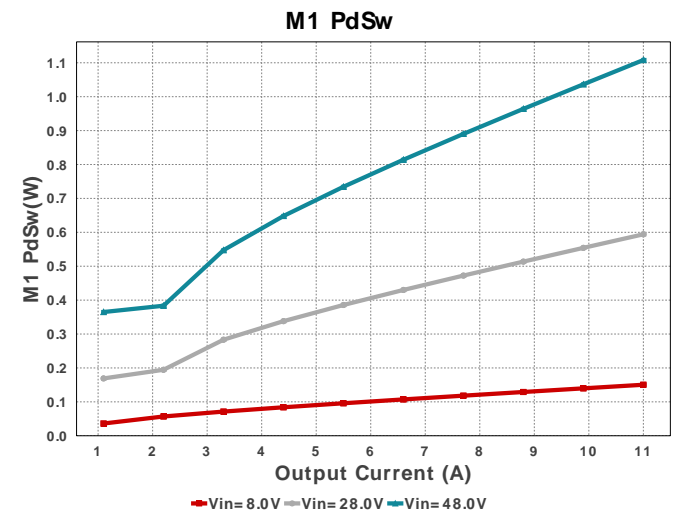
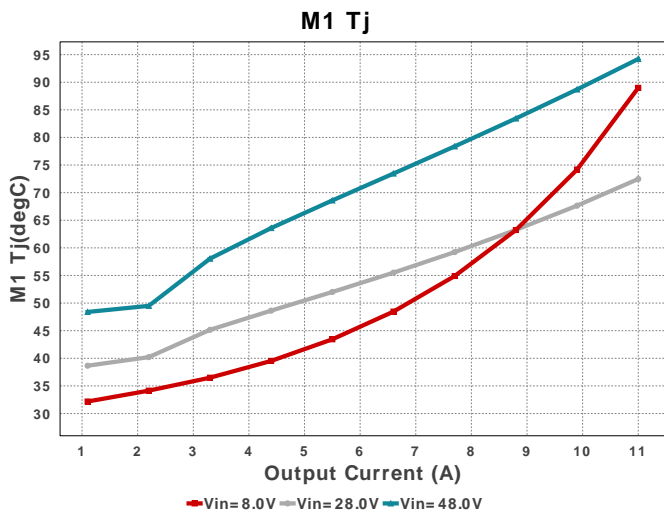
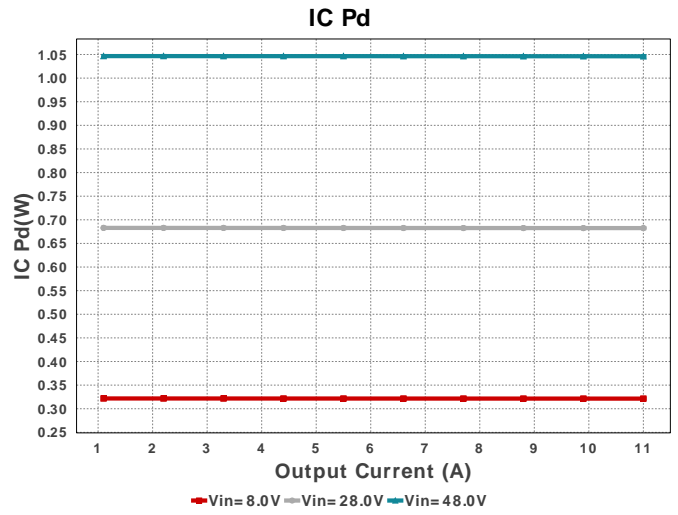
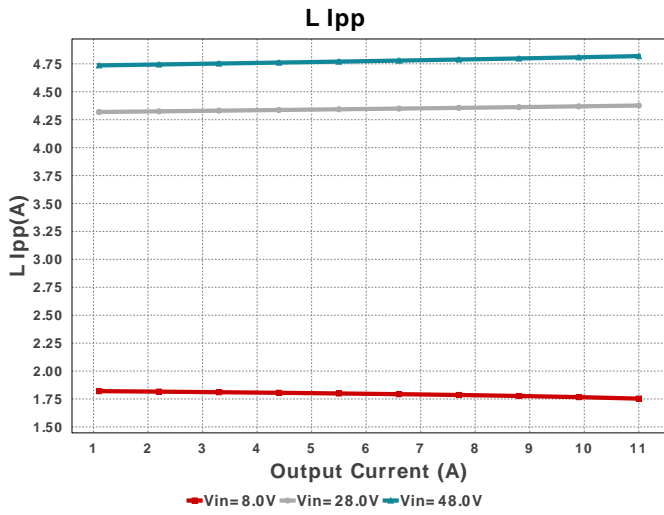


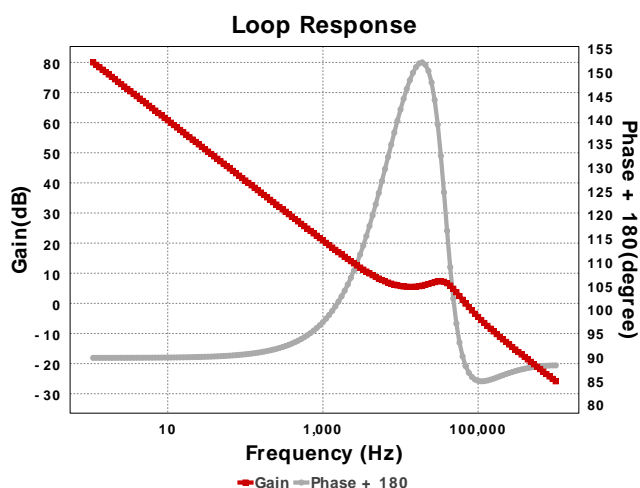
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cvcc	TDK	C1005X5R1V225K050BC Series= X5R	Cap= 2.2 uF ESR= 1.0 mOhm VDC= 35.0 V IRMS= 0.0 A	1	\$0.07	 0402_065 3 mm ²
Cvin	TDK	C1608X7S2A104K080AB Series= X7S	Cap= 100.0 nF ESR= 49.59 mOhm VDC= 100.0 V IRMS= 751.62 mA	1	\$0.03	 0603 5 mm ²
L1	Coilcraft	XAL7070-182MEB	L= 1.8 uH 4.1 mOhm	1	\$1.19	 XAL7070 87 mm ²
M1	Texas Instruments	CSD18533Q5A	VdsMax= 60.0 V IdsMax= 100.0 Amps	1	\$0.50	 DQJ0008A 55 mm ²
M2	Infineon Technologies	BSC037N08NS5ATMA1	VdsMax= 80.0 V IdsMax= 100.0 Amps	1	\$1.06	 PG-TDSON-8 55 mm ²
Rcomp1	Vishay-Dale	CRCW04021K74FKED Series= CRCW..e3	Res= 1.74 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rcomp2	Vishay-Dale	CRCW040247R5FKED Series= CRCW..e3	Res= 47.5 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rfbf	Vishay-Dale	CRCW04023K24FKED Series= CRCW..e3	Res= 3.24 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rfbt	Yageo	RC0603FR-0718KL Series= ?	Res= 18.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm ²
Rilim	Vishay-Dale	CRCW04021K13FKED Series= CRCW..e3	Res= 1.13 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rpgood	Vishay-Dale	CRCW040220K0FKED Series= CRCW..e3	Res= 20.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rt	Vishay-Dale	CRCW040218K2FKED Series= CRCW..e3	Res= 18.2 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Ruv1	Vishay-Dale	CRCW040240K2FKED Series= CRCW..e3	Res= 40.2 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Ruv2	Yageo	RC0603FR-078K87L Series= ?	Res= 8.87 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm ²
Rvcc	Vishay-Dale	CRCW040220K0FKED Series= CRCW..e3	Res= 20.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rvin	Vishay-Dale	CRCW06032R10FKEA Series= CRCW..e3	Res= 2.1 Ohm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm ²
U1	Texas Instruments	LM5145RGYR	Switcher	1	\$2.30	 RGY0020B 25 mm ²











Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	3.5 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	28.581 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	1.391 A	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	1.936 mW	Capacitor	Output capacitor power dissipation
5.	IC Ipk	13.41 A	IC	Peak switch current in IC
6.	IC Pd	1.046 W	IC	IC power dissipation
7.	IC Tj	66.408 degC	IC	IC junction temperature
8.	IC Tolerance	8.0 mV	IC	IC Feedback Tolerance
9.	ICThetaJA	34.8 degC/W	IC	IC junction-to-ambient thermal resistance
10.	Iin Avg	1.298 A	IC	Average input current
11.	Ipp percentage	43.812 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
12.	L Ipp	4.819 A	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	504.04 mW	Inductor	Inductor power dissipation
14.	M1 Pd	1.284 W	Mosfet	M1 MOSFET total power dissipation
15.	M1 PdCond	176.06 mW	Mosfet	M1 MOSFET conduction losses
16.	M1 PdSw	1.108 W	Mosfet	M1 MOSFET switching losses
17.	M1 Tj	94.21 degC	Mosfet	M1 MOSFET junction temperature
18.	M2 Pd	1.682 W	Mosfet	M2 MOSFET total power dissipation
19.	M2 PdCond	717.48 mW	Mosfet	M2 MOSFET conduction losses
20.	M2 PdSw	964.81 mW	Mosfet	M2 MOSFET switching losses
21.	M2 Tj	114.11 degC	Mosfet	M2 MOSFET junction temperature
22.	Cin Pd	28.581 mW	Power	Input capacitor power dissipation
23.	Cout Pd	1.936 mW	Power	Output capacitor power dissipation
24.	IC Pd	1.046 W	Power	IC power dissipation
25.	L Pd	504.04 mW	Power	Inductor power dissipation
26.	M1 Pd	1.284 W	Power	M1 MOSFET total power dissipation
27.	M1 PdCond	176.06 mW	Power	M1 MOSFET conduction losses
28.	M1 PdSw	1.108 W	Power	M1 MOSFET switching losses
29.	M2 Pd	1.682 W	Power	M2 MOSFET total power dissipation
30.	M2 PdCond	717.48 mW	Power	M2 MOSFET conduction losses
31.	M2 PdSw	964.81 mW	Power	M2 MOSFET switching losses
32.	Total Pd	4.548 W	Power	Total Power Dissipation
33.	BOM Count	29	System	Total Design BOM count
34.	Cross Freq	69.037 kHz	Information	Bode plot crossover frequency
35.	Duty Cycle	11.198 %	System	Duty cycle
36.	Efficiency	92.699 %	Information	Steady state efficiency
37.	FootPrint	354.0 mm ²	System	Total Foot Print Area of BOM components
38.	Frequency	549.451 kHz	Information	Switching frequency
39.	Gain Marg	-108.536 dB	System	Bode Plot Gain Margin
40.	Iout	11.0 A	Information	Iout operating point
41.	Low Freq Gain	79.994 dB	System	Gain at 1Hz

#	Name	Value	Category	Description
42.	Mode	CCM	System Information	Conduction Mode
43.	Phase Marg	88.301 deg	System Information	Bode Plot Phase Margin
44.	Pout	57.75 W	System Information	Total output power
45.	Total BOM	\$7.57	System Information	Total BOM Cost
46.	Vin	48.0 V	System Information	Vin operating point
47.	Vout	5.25 V	System Information	Operational Output Voltage
48.	Vout Actual	5.244 V	System Information	Vout Actual calculated based on selected voltage divider resistors
49.	Vout Tolerance	2.729 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
50.	Vout p-p	109.751 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	11.0	Maximum Output Current
VinMax	48.0	Maximum input voltage
VinMin	8.0	Minimum input voltage
Vout	5.25	Output Voltage
base_pn	LM5145	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

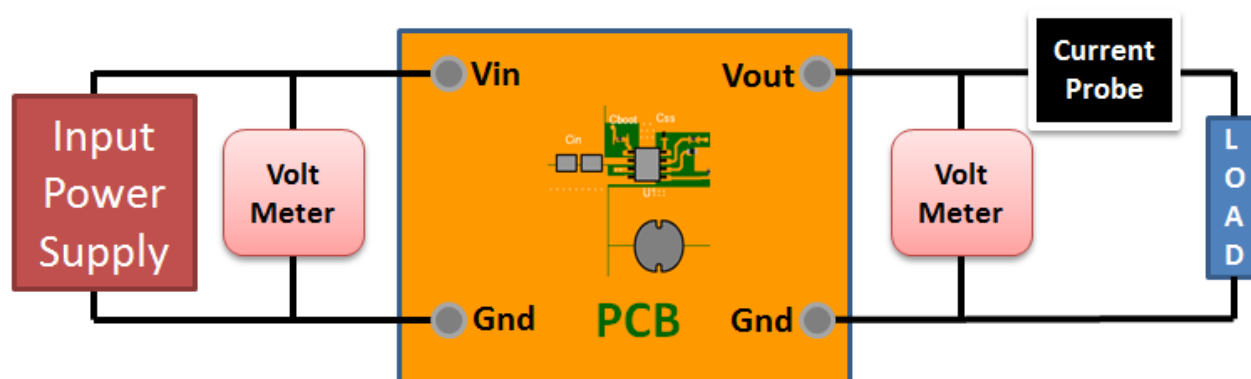
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 8.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : C63A496462E56C13[v1]
2. **LM5145** Product Folder : <http://www.ti.com/product/lm5145> : contains the data sheet and other resources.

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